Not Recommended for New Design Alternative is BCP56 & BCP5616



DCP56/-16

NPN SURFACE MOUNT TRANSISTOR

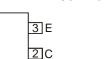
Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DCP53)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.115 grams (approximate)

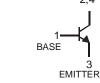




1 B

TOP VIEW

С



COLLECTOR

Schematic and Pin Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	80	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current	Ic	1	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ T _A = 25°C (Note 3)	P_d	1	W
Operating and Storage Temperature Range	T_j , T_{STG}	-55 to 150	°C
Thermal Resistance, Junction to Ambient Air @T _A = 25°C (Note 3)	$R_{ hetaJA}$	125	°C/W

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)		•		•		
Collector-Base Breakdown Voltage	V _{(BR)CBO}	100	_	_	V	$I_C = 100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	80	_	_	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	5.0	_	_	V	$I_E = 10 \mu A, I_C = 0$
Collector-Base Cutoff Current	I _{CBO}	_	_	0.1 20	μА	$V_{CB} = 30V, I_E = 0$ $V_{CB} = 30V, I_E = 0, T_A = 150$ °C
Emitter-Base Cutoff Current	I _{EBO}	_	_	10	μА	$V_{EB} = 5.0V, I_C = 0$
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h _{FE}	25 40 25		 250 	_	$\begin{split} I_{C} &= 5.0 \text{mA}, & V_{CE} = 2.0 \text{V} \\ I_{C} &= 150 \text{mA}, & V_{CE} = 2.0 \text{V} \\ I_{C} &= 500 \text{mA}, & V_{CE} = 2.0 \text{V} \end{split}$
DCP56-16		100	160	250		$I_C = 150 \text{mA}, \ V_{CE} = 2.0 \text{V}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	_	0.5	V	I _C = 500mA, I _B = 50mA
Base-Emitter Turn-On Voltage	V _{BE (ON)}	_	_	1.0	V	$I_C = 500$ mA, $V_{CE} = 2.0$ V
SMALL SIGNAL CHARACTERISTICS						
Current-Gain-Bandwidth Product	f⊤	_	200	_	MHz	I _C = 50mA, V _{CE} = 5.0V, f = 100MHz

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 4. Pulse Test: Pulse width = ≤300μs, Duty Cycle ≤ 2%.

DCP56/-16 Document number: DS30796 Rev. 7 - 3



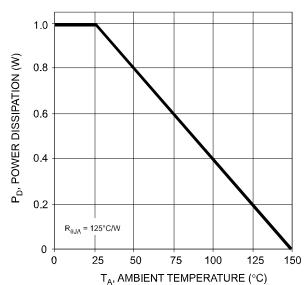


Fig. 1 Power Dissipation vs. Ambient Temperature

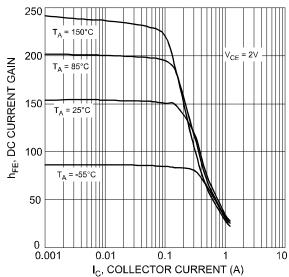
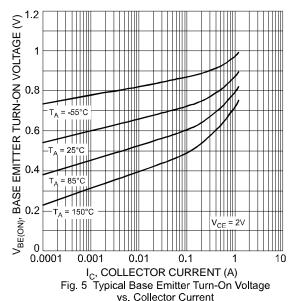
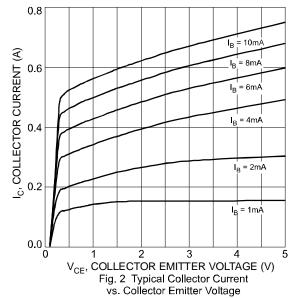


Fig. 3 Typical DC Current Gain vs. Collector Current





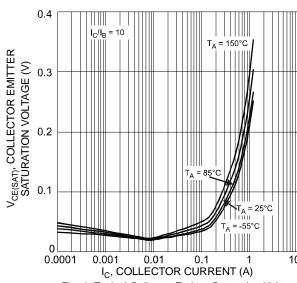


Fig. 4 Typical Collector Emitter Saturation Voltage vs. Collector Current

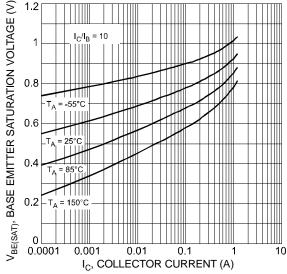
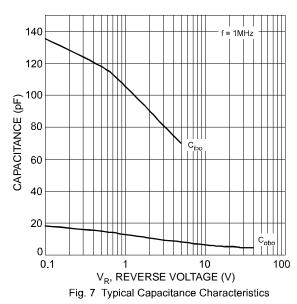


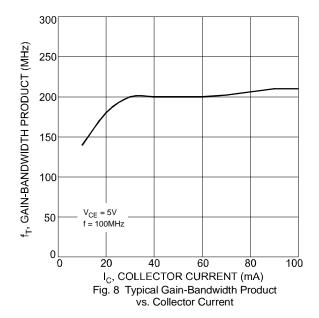
Fig. 6 Typical Base Emitter Saturation Voltage vs. Collector Current

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Not Recommended for New Design Alternative is BCP56 & BCP5616



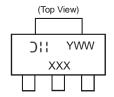


Ordering Information (Note 5)

Device	Packaging	Shipping
DCP56-13	SOT-223	2500/Tape & Reel
DCP56-16-13	SOT-223	2500/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

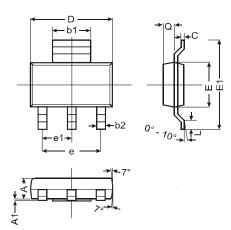
Marking Information



XXX = Product Type Marking Code ex. N18 = DCP56 N18-16 = DCP56-16

OII = Manufacturer's Marking Code YWW = Date Code Marking Y = Last Digit of Year ex: 7 = 2007 WW = Week Code 01-52

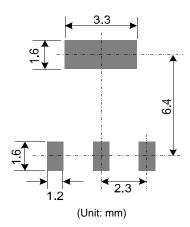
Package Outline Dimensions



SOT-223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b1	2.90	3.10	3.00		
b2	0.60	0.80	0.70		
C	0.20	0.30	0.25		
D	6.45	6.55	6.50		
E	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е			4.60		
e1			2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					



Suggested Pad Layout: (Based on IPC-SM-782)



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